2SK2590

Silicon N-Channel MOS FET

HITACHI

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Preliminary

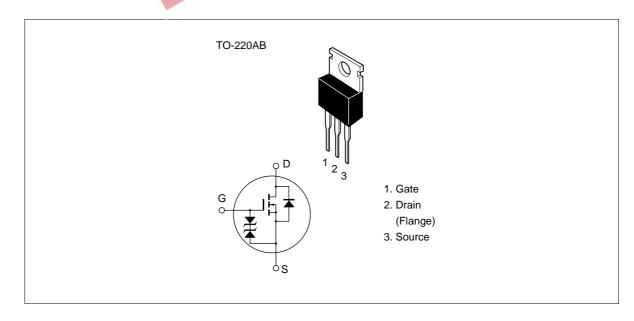
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No Secondary Breakdown
- Suitable for Switching regulator, DC-DC converter, Motor Control

Outline





2SK2590

Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit				
Drain to source voltage	V _{DSS}	200	V				
Gate to source voltage	V_{GSS}	±20	V				
Drain current	I _D	7	A				
Drain peak current	I _{D(pulse)} *1	28	A				
Body to drain diode reverse drain current	I _{DR}	7	A				
Channel dissipation	Pch*2	50	W				
Channel temperature	Tch	150	°C				
Storage temperature	Tstg	-55 to +150	°C				
Notes 1. PW ≤ 10 µs, duty cycle ≤ 1 % 2. Value at Tc = 25 °C							



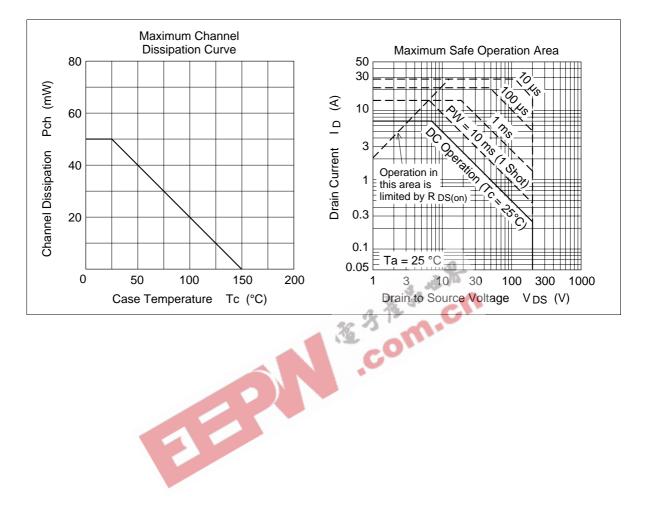
Electrical Characteristics (Ta = 25°C)

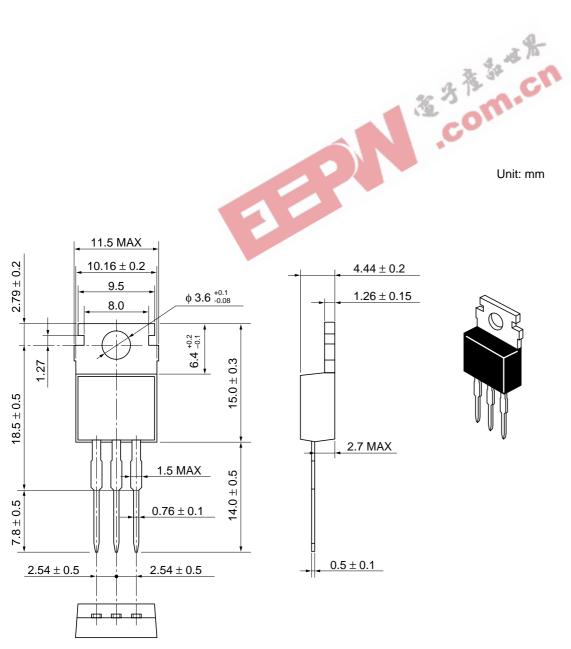
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	200	_	_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	250	μΑ	$V_{DS} = 160 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	4.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state resistance	$R_{DS(on)}$	_	0.33	0.45	Ω	$I_D = 4 A$ $V_{GS} = 10 V^{*1}$
Forward transfer admittance	y _{fs}	3.0	4.5	_	S	$I_{D} = 4 \text{ A}$ $V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	700	_	pF	V _{DS} = 10 V
Output capacitance	Coss	_	260	- 為	pF	$V_{gs} = 0$
Reverse transfer capacitance	Crss	_	45	25	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	-	20	7:0	ns	I _D = 4 A
Rise time	t _r	$\frac{4}{3}$	45	1	ns	$V_{GS} = 10 \text{ V}$
Turn-off delay time	$t_{d(off)}$	-) \	50	_	ns	$R_L = 7.5\Omega$
Fall time	t _i		35	_	ns	_
Body to drain diode forward voltage	V _{DF}		1.1	_	V	$I_F = 7 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	150	_	ns	$I_F = 7 \text{ A}, V_{GS} = 0,$ $di_F / dt = 100 \text{ A} / \mu \text{s}$

Note 1. Pulse Test

See characteristics curves of 2SK1957.

2SK2590





Hitachi Code	TO-220AB
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	1 8 a

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